

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

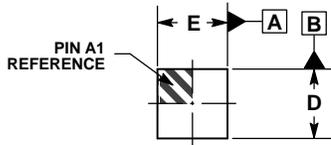
ON Semiconductor®



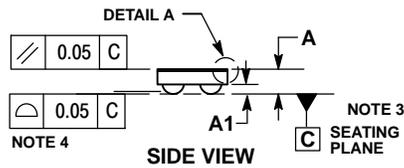
SCALE 4:1

WLCSP4, 0.77x0.77x0.3
CASE 567PN
ISSUE O

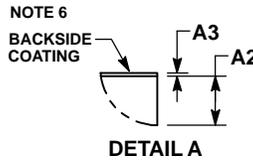
DATE 11 AUG 2016



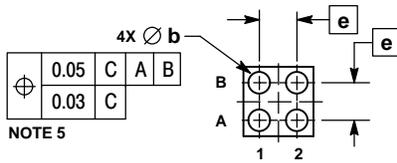
TOP VIEW



SIDE VIEW

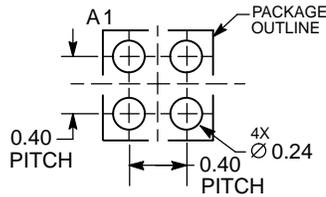


DETAIL A



BOTTOM VIEW

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. COPLANARITY APPLIES TO SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.
6. BACKSIDE COATING IS OPTIONAL.

MILLIMETERS			
DIM	MIN	NOM	MAX
A	---	---	0.30
A1	0.09	0.11	0.13
A2	0.14 REF		
A3	0.025 REF		
b	0.22	0.24	0.26
D	0.75	0.77	0.79
E	0.75	0.77	0.79
e	0.40 BSC		

GENERIC MARKING DIAGRAM*



- X = Specific Device Code
- Y = Year
- W = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

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NEW STANDARD:		
DESCRIPTION:	WLCSP4, 0.77X0.77X0.3	PAGE 1 OF 2

